1. Record Nr. UNISALENTO991003443039707536

Autore	Sciacca, Michele Federico
Titolo	L'uomo questo "squilibrato" : saggio sulla condizione umana / M. F. Sciacca
Pubbl/distr/stampa	[Roma] : Fratelli Bocca, stampa 1956
Descrizione fisica	331 p. ; 21 cm.
Collana	Opere complete di Michele Federico Sciacca ; 5
Lingua di pubblicazione	Italiano
Formato	Materiale a stampa
Livello bibliografico	Monografia

2. Record Nr. UNINA9911004740003321

Titolo	Electromigration in thin films and electronic devices : materials and reliability / / edited by Choong-Un Kim
Pubbl/distr/stampa	Oxford ; ; Philadelphia, : Woodhead Pub., c2011
ISBN	9780857093752 0857093754
Edizione	[1st edition]
Descrizione fisica	1 online resource (353 p.)
Collana	Woodhead Publishing Series in Electronic and Optical Materials
Altri autori (Persone)	KimChoong-Un
Disciplina	621.38152
Soggetti	Integrated circuits - Deterioration Electrodiffusion Thin films Interconnects (Integrated circuit technology)
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Part I. Introduction. Modeling electromigration phenomena / F. Cacho and X. Federspiel ; Modeling electromigratoin using the peridynamics approach / D.T. Read and V.K. Tewary and W.H. Gerstle ; Modeling,

simulation and X-ray microbeam studies of electromigration / A.M. Maniatty, G.S. Cargill III, and H. Zhang -- Part II. Electromigration in copper interconnects. X-ray microbeam analysis of electromigration in copper inteerconnects / H. Zhang and G.S. Cargill III ; Voiding in copper interconnects during electromigration / C.L. Gan and M.K. Lim ; The evolution of microstructure in copper interconnects during electromigration / A.S> Budiman ; Scaling effects on electromigration reliability of copper interconnects / L. Zhang, J.W. Pyun, and P.S. Ho ; Electromigration failure in nanoscale copper interconnects / E.T. Ogawa -- Part III. Electromigration in solder. Electromigration-induced microstructural evolution in lead-free and lead-tin solders / K.-L. Lin ; Electromigration in flip-chip solder joints / D. Yang and Y.C. Chan and M. Pecht.

Sommario/riassunto

Understanding and limiting electromigration in thin films is essential to the continued development of advanced copper interconnects for integrated circuits. Electromigration in thin films and electronic devices provides an up-to-date review of key topics in this commercially important area.Part one consists of three introductory chapters, covering modelling of electromigration phenomena, modelling electromigration using the peridynamics approach and simulation and x-ray microbeam studies of electromigration. Part two deals with electromigration issues in copper interconnects, includin